



High-Side, Bidirectional CURRENT SHUNT MONITOR

FEATURES

- COMPLETE BIDIRECTIONAL CURRENT MEASUREMENT CIRCUIT
- WIDE SUPPLY RANGE: 2.7V to 40V
- SUPPLY-INDEPENDENT COMMON-MODE VOLTAGE: 2.7V TO 60V
- RESISTOR PROGRAMMABLE GAIN SET
- LOW QUIESCENT CURRENT: 75 μ A (typ)
- MSOP-8 PACKAGE

APPLICATIONS

- CURRENT SHUNT MEASUREMENT:
Automotive, Telephone, Computers, Power Systems, Test, General Instrumentation
- PORTABLE AND BATTERY-BACKUP SYSTEMS
- BATTERY CHARGERS
- POWER MANAGEMENT
- CELL PHONES

DESCRIPTION

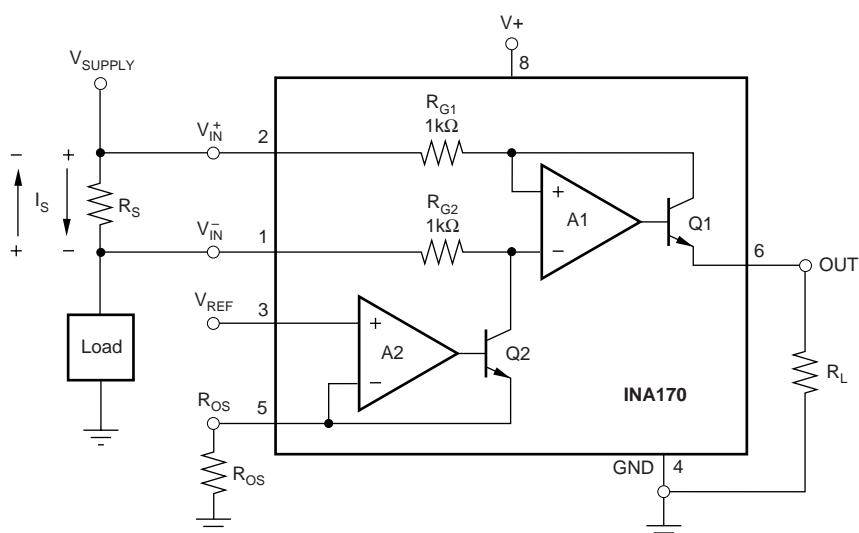
The INA170 is a high-side, bidirectional current shunt monitor featuring a wide input common-mode voltage range, low quiescent current, and a tiny MSOP-8 package.

Bidirectional current measurement is accomplished by output offsetting. The offset voltage level is set with an external resistor and voltage reference. This permits measurement of a bidirectional shunt current while using a single supply for the INA170.

Input common-mode and power-supply voltages are independent. Input voltage can range from +2.7V to +60V on any supply voltage from +2.7V to +40V. Low 10 μ A input bias current adds minimal error to the shunt current.

The INA170 converts a differential input voltage to a current output. This current develops a voltage across an external load resistor, setting any gain from 1 to over 100.

The INA170 is available in an MSOP-8 package, and is specified over the extended industrial temperature range, -40°C to +85°C with operation from -55°C to +125°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Supply Voltage, V+ to GND	-0.3V to 40V
Analog Inputs, Common Mode ⁽²⁾	-0.3V to 75V
Differential (V _{IN} ⁺) - (V _{IN} ⁻)	-40V to 2V
Analog Output, Out ⁽²⁾	-0.3V to 40V
Input Current Into Any Pin	10mA
Operating Temperature	-55°C to +125°C
Storage Temperature	-65°C to +150°C
Junction Temperature	+150°C

NOTE: (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied. (2) The input voltage at any pin may exceed the voltage shown if the current at that pin is limited to 10mA.



ELECTROSTATIC DISCHARGE SENSITIVITY

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

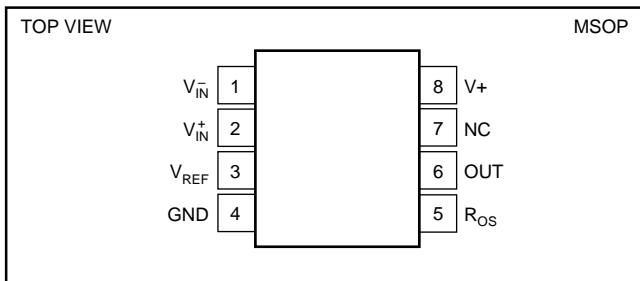
ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION⁽¹⁾

PRODUCT	PACKAGE-LEAD	PACKAGE DESIGNATOR	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
INA170EA	MSOP-8	DGK	-40°C to +85°C	INA170EA	INA170EA/250	Tape and Reel, 250
"	"	"	"	"	INA170EA/2K5	Tape and Reel, 2500

NOTE: (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

PIN CONFIGURATION



PIN DESCRIPTION

PIN	DESIGNATOR	DESCRIPTION
1	V _{IN} ⁻	Inverting Input
2	V _{IN} ⁺	Noninverting Input
3	V _{REF}	Reference Voltage Input
4	GND	Ground
5	R _{OS}	Offset Resistor
6	OUT	Output
7	NC	No Connection
8	V ₊	Supply Voltage

ELECTRICAL CHARACTERISTICS

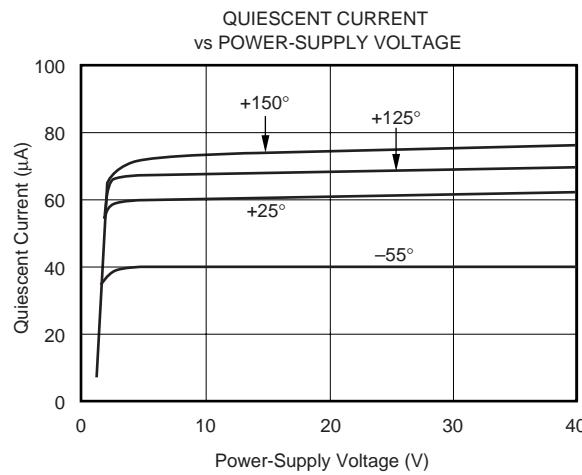
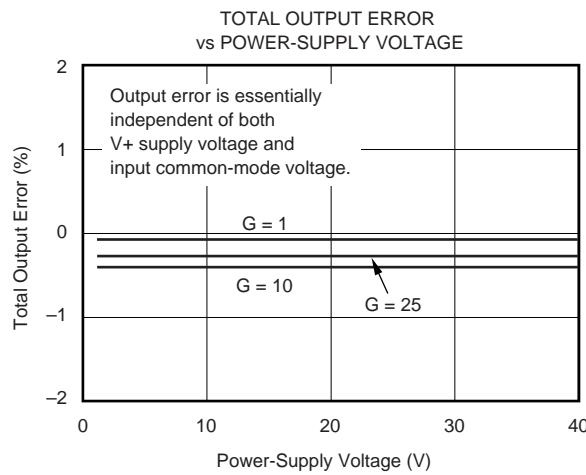
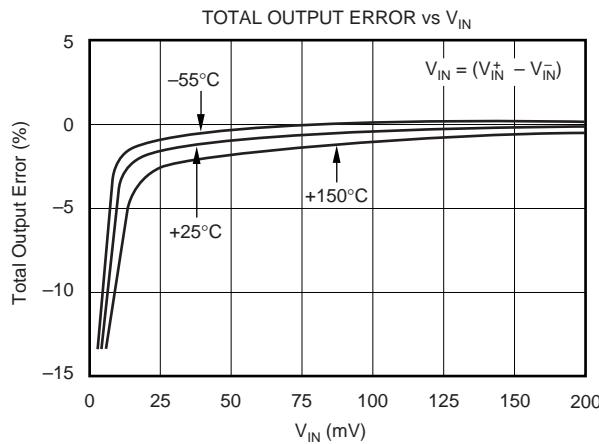
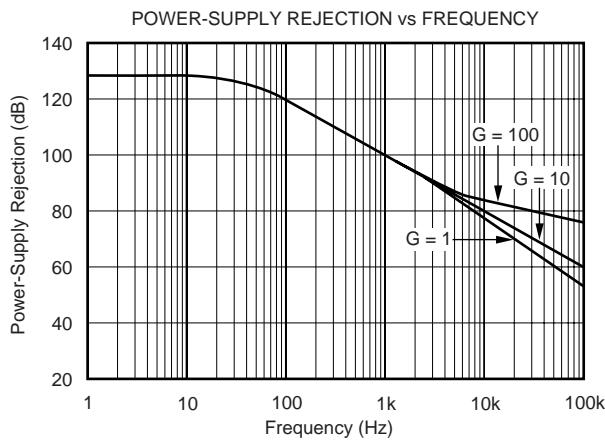
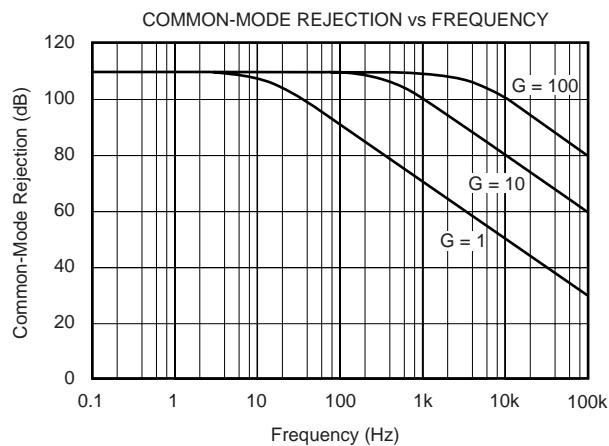
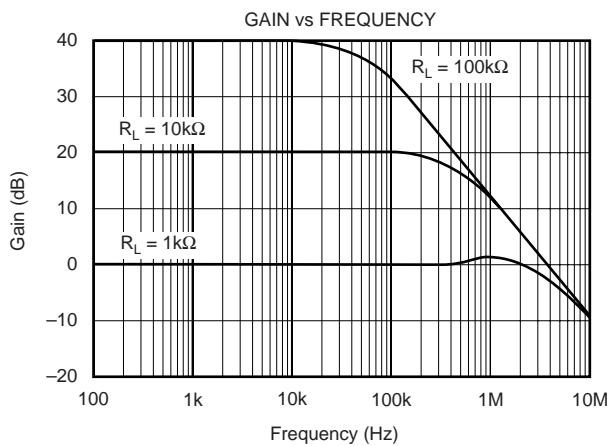
At $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$, $V_S = 5\text{V}$, $V_{IN}^+ = 12\text{V}$, $R_{OUT} = 25\text{k}\Omega$, unless otherwise noted.

PARAMETER	CONDITION	INA170EA			UNITS
		MIN	TYP	MAX	
INPUT					
Full-Scale Sense (Input) Voltage	$V_{SENSE} = V_{IN}^+ - V_{IN}^-$		100	500	mV
Common-Mode Input Range	$V_{IN}^+ = +2.7\text{V}$ to $+60\text{V}$, $V_{SENSE} = 50\text{mV}$	+2.7	120	+60	V
Common-Mode Rejection		100	± 0.2	± 1	dB
Offset Voltage ⁽¹⁾ RTI			1		mV
vs Temperature	T_{MIN} to T_{MAX}		0.1		$\mu\text{V}/^\circ\text{C}$
vs Power Supply	$V_+ = +2.7\text{V}$ to $+60\text{V}$, $V_{SENSE} = 50\text{mV}$		10		$\mu\text{V}/\text{V}$
Input Bias Current	V_{IN}^+, V_{IN}^-				uA
OFFSETTING AMPLIFIER					
Offsetting Equation	$V_{OS} = (R_L/R_{OS}) V_{REF}$	1			
Input Voltage			± 0.2	$V_S - 1$	V
Input Offset Voltage			10	± 1	mV
vs Temperature	T_{MIN} to T_{MAX}	0		1	$\mu\text{V}/^\circ\text{C}$
Programming Current through R_{OS}					mA
Input Impedance			$10^{10} \parallel 4$		$\Omega \parallel \text{pF}$
Input Bias Current	V_{IN}^+, V_{IN}^-		+10		nA
OUTPUT					
Transconductance	$V_{SENSE} = 10\text{mV}$ to 150mV	0.990	1	1.01	mA/V
vs Temperature	$V_{SENSE} = 100\text{mV}$		50		$\text{nA}/^\circ\text{C}$
Nonlinearity Error	$V_{SENSE} = 10\text{mV}$ to 150mV		± 0.01	± 0.1	%
Total Output Error	$V_{SENSE} = 100\text{mV}$		± 0.5	± 2	%
Output Impedance			1 \parallel 5		$\text{G}\Omega \parallel \text{pF}$
Voltage Output					
Swing to Power Supply, V_+			$(V_+) - 0.9$	$(V_+) - 1.2$	V
Swing to Common Mode, V_{CM}			$V_{CM} - 0.6$	$V_{CM} - 1.0$	V
FREQUENCY RESPONSE					
Bandwidth	$R_{OUT} = 10\text{k}\Omega$		400		kHz
Settling Time (0.1%)	5V Step, $R_{OUT} = 10\text{k}\Omega$		3		μs
NOISE					
Output-Current Noise Density			20		$\text{pA}/\sqrt{\text{Hz}}$
Total Output-Current Noise	$BW = 100\text{kHz}$		7		nA RMS
POWER SUPPLY					
Operating Range	V_+	+2.7			V
Quiescent Current	$V_{SENSE} = 0, I_O = 0$		75	+40	μA
				125	
TEMPERATURE RANGE					
Specification, T_{MIN} to T_{MAX}					$^\circ\text{C}$
Operating		-40		+85	$^\circ\text{C}$
Storage		-55		+125	$^\circ\text{C}$
Thermal Resistance, θ_{JA}		-65		+150	$^\circ\text{C}/\text{W}$
			150		

NOTE: (1) Defined as the amount of input voltage, V_{SENSE} , to drive the output to zero.

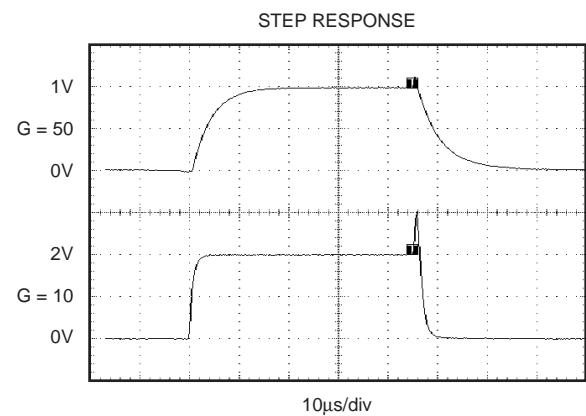
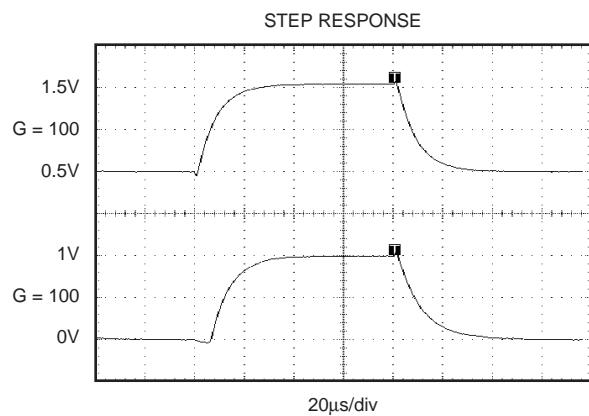
TYPICAL CHARACTERISTICS

At $T_A = +25^\circ\text{C}$, $V_+ = 5\text{V}$, $V_{IN}^+ = 12\text{V}$, $R_L = 25\text{k}\Omega$, unless otherwise noted.



TYPICAL CHARACTERISTICS (Cont.)

At $T_A = +25^\circ\text{C}$, $V+ = 5\text{V}$, $V_{IN}^+ = 12\text{V}$, $R_L = 25\text{k}\Omega$, unless otherwise noted.



OPERATION

Figure 1 shows the basic circuit diagram for the INA170. Load current I_S is drawn from supply V_S through shunt resistor R_S . The voltage drop in shunt resistor V_S is forced across R_{G1} by the internal op-amp, causing current to flow into the collector of Q1. External resistor R_L converts the output current to a voltage, V_{OUT} , at the OUT pin.

Without offset, the transfer function for the INA170 is:

$$I_O = g_m (V_{IN}^+ - V_{IN}^-) \quad (1)$$

$$\text{where } g_m = 1000\mu\text{A/V} \quad (2)$$

In the circuit of Figure 1, the input voltage, $(V_{IN}^+ - V_{IN}^-)$, is equal to $I_S \cdot R_S$ and the output voltage, V_{OUT} , is equal to $I_O \cdot R_L$. The transconductance, g_m , of the INA170 is $1000\mu\text{A/V}$. The complete transfer function for the current measurement amplifier in this application is:

$$V_{OUT} = (I_S) (R_S) (1000\mu\text{A/V}) (R_L) \quad (3)$$

Applying a positive reference voltage to pin 3 causes a current to flow through R_{OS} , forcing output current I_O to be offset from zero. The transfer function then becomes:

$$V_{OUT} = \left(\frac{V_{REF} \cdot R_L}{R_{OS}} \right) \pm \left(\frac{I_S \cdot R_S \cdot R_L}{1\text{k}\Omega} \right) \quad (4)$$

The maximum differential input voltage for accurate measurements is 0.5V , which produces a $500\mu\text{A}$ output current. A differential input voltage of up to 2V will not cause damage. Differential measurements (pins 1 and 2) can be

bipolar with a more-positive voltage applied to pin 2. If a more-negative voltage is applied to pin 1, output current I_O will decrease towards zero.

BASIC CONNECTION

Figure 1 shows the basic connection of the INA170. The input pins, V_{IN}^+ and V_{IN}^- , should be connected as closely as possible to the shunt resistor to minimize any resistance in series with the shunt resistance. The output resistor, R_L , is shown connected between pin 6 and ground. Best accuracy is achieved with the output voltage measured directly across R_L . This is especially important in high-current systems where load current could flow in the ground connections, affecting the measurement accuracy.

No power-supply bypass capacitors are required for stability of the INA170. However, applications with noisy or high impedance power supplies may require de-coupling capacitors to reject power-supply noise. Connect bypass capacitors close to the device pins.

POWER SUPPLIES

The input circuitry of the INA170 can accurately measure beyond its power-supply voltage, V_+ . For example, the V_+ power supply can be 5V , while the load power-supply voltage (INA170 input voltage) is up to $+60\text{V}$. However, the output-voltage range of the OUT terminal (pin 6) is limited by the supply.

SELECTING R_S AND R_L

The value chosen for the shunt resistor, R_S , depends on the application and is a compromise between small-signal accuracy and maximum permissible voltage loss in the measurement line. High values of R_S provide better accuracy at lower

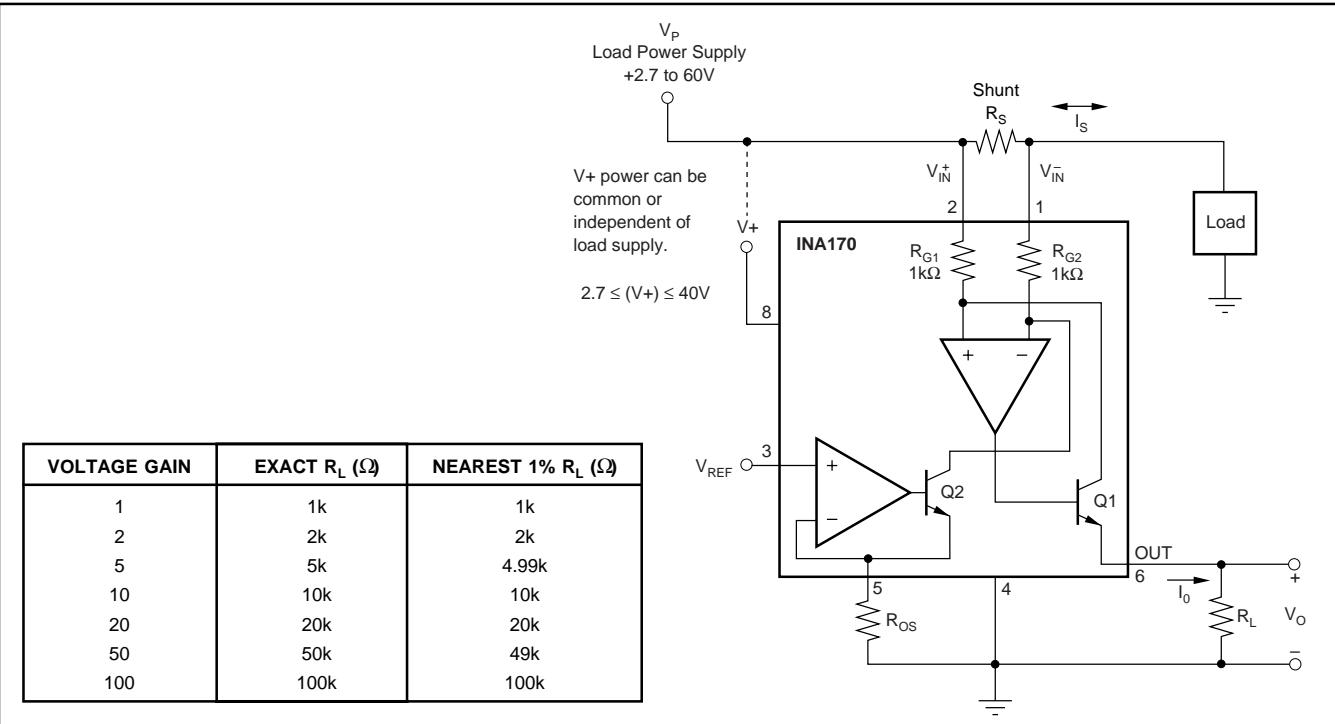


FIGURE 1. Basic Circuit Connections.

currents by minimizing the effects of offset, while low values of R_S minimize voltage loss in the supply line. For most applications, best performance is attained with an R_S value that provides a full-scale shunt voltage of 50mV to 100mV. Maximum input voltage for accurate measurements is 500mV.

R_L is chosen to provide the desired full-scale output voltage. The output impedance of the INA170 Out terminal is very high which permits using values of R_L up to 100k Ω with excellent accuracy. The input impedance of any additional circuitry at the output should be much higher than the value of R_L to avoid degrading accuracy.

Some Analog-to-Digital (A/D) converters have input impedances that will significantly affect measurement gain. The input impedance of the A/D converter can be included as part of the effective R_L if its input can be modeled as a resistor to ground. Alternatively, an op-amp can be used to buffer the A/D converter input, as shown in Figure 2. See Figure 1 for recommended values of R_L .

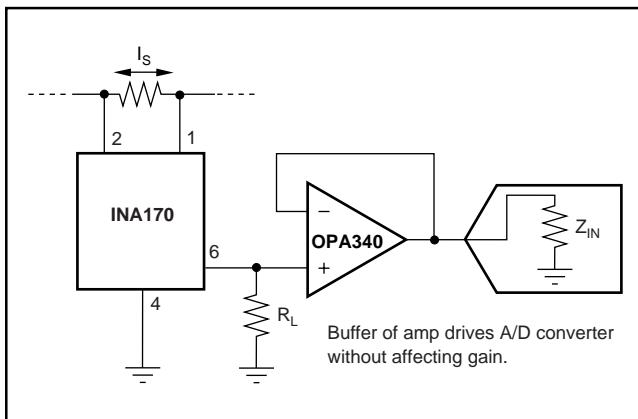


FIGURE 2. Buffering Output to Drive A/D Converter.

OUTPUT VOLTAGE RANGE

The output of the INA170 is a current, which is converted to a voltage by the load resistor, R_L . The output current remains accurate within the *compliance voltage range* of the output circuitry. The shunt voltage and the input common-mode and power supply voltages limit the maximum possible

output swing. The maximum output voltage compliance is limited by the lower of the two equations below:

$$V_{out\ max} = (V+) - 0.7V - (V_{IN}^+ - V_{IN}^-) \quad (5)$$

or

$$V_{out\ max} = V_{IN}^- - 0.5V \quad (6)$$

(whichever is lower)

BANDWIDTH

Measurement bandwidth is affected by the value of the load resistor, R_L . High gain produced by high values of R_L will yield a narrower measurement bandwidth (see Typical Characteristic Curves). For widest possible bandwidth, keep the capacitive load on the output to a minimum.

If bandwidth limiting (filtering) is desired, a capacitor can be added to the output, as shown in Figure 3. This will not cause instability.

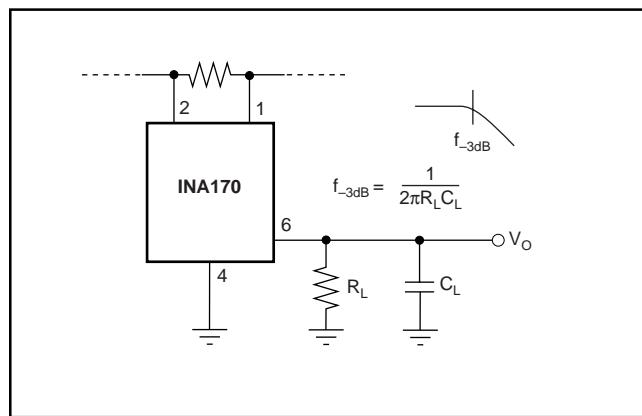


FIGURE 3. Output Filter.

APPLICATIONS

The INA170 is designed for current shunt measurement circuits as shown in Figure 1, but its basic function is useful in a wide range of circuitry. A creative engineer will find many unforeseen uses in measurement and level shifting circuits.

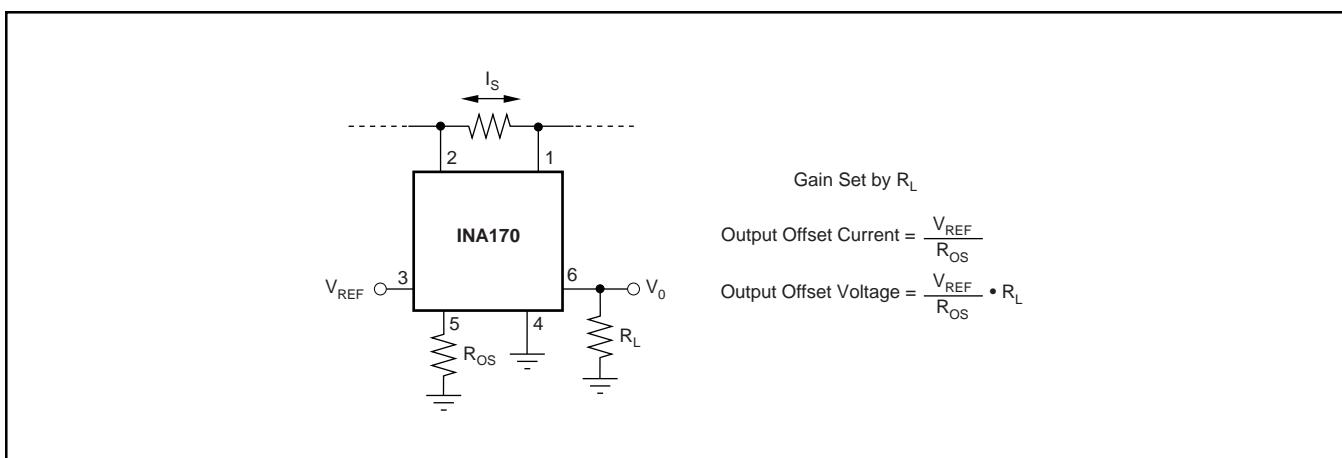


FIGURE 4. Offsetting the Output Voltage.

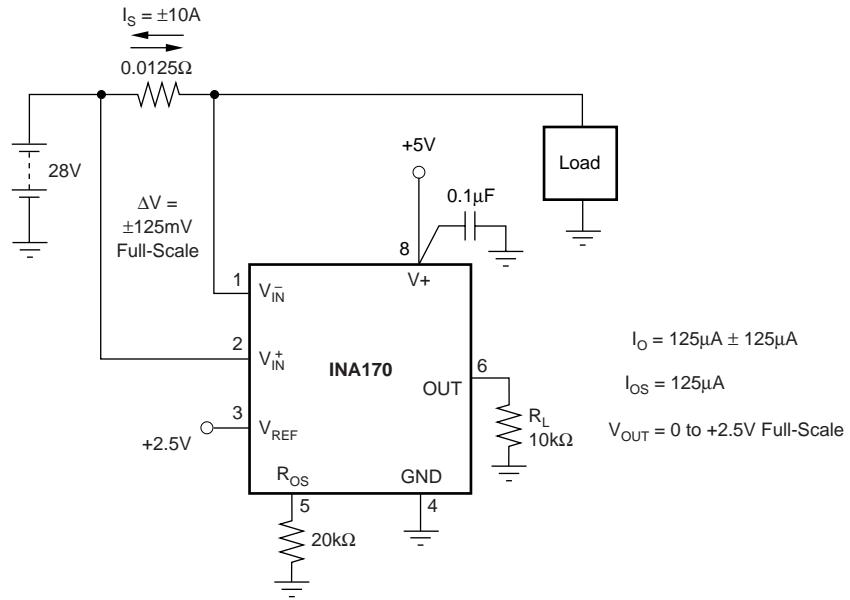


FIGURE 5. Bipolar Current Measurement.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
INA170EA/2K5	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	A70
INA170EA/2K5.A	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	A70

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

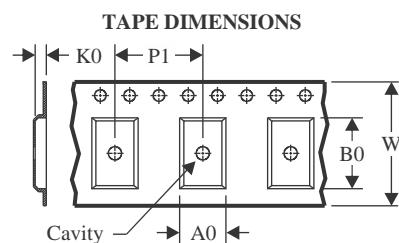
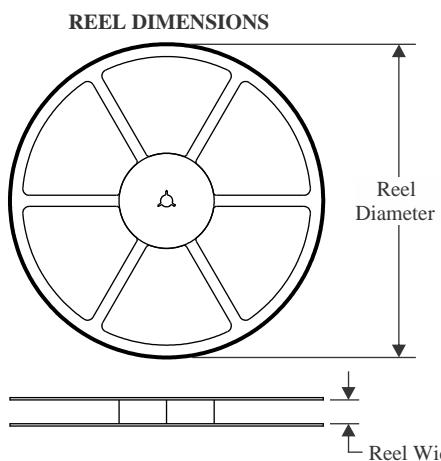
⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

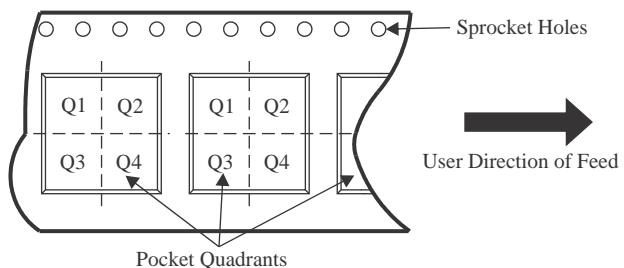
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
INA170EA/2K5	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
INA170EA/2K5	VSSOP	DGK	8	2500	366.0	364.0	50.0

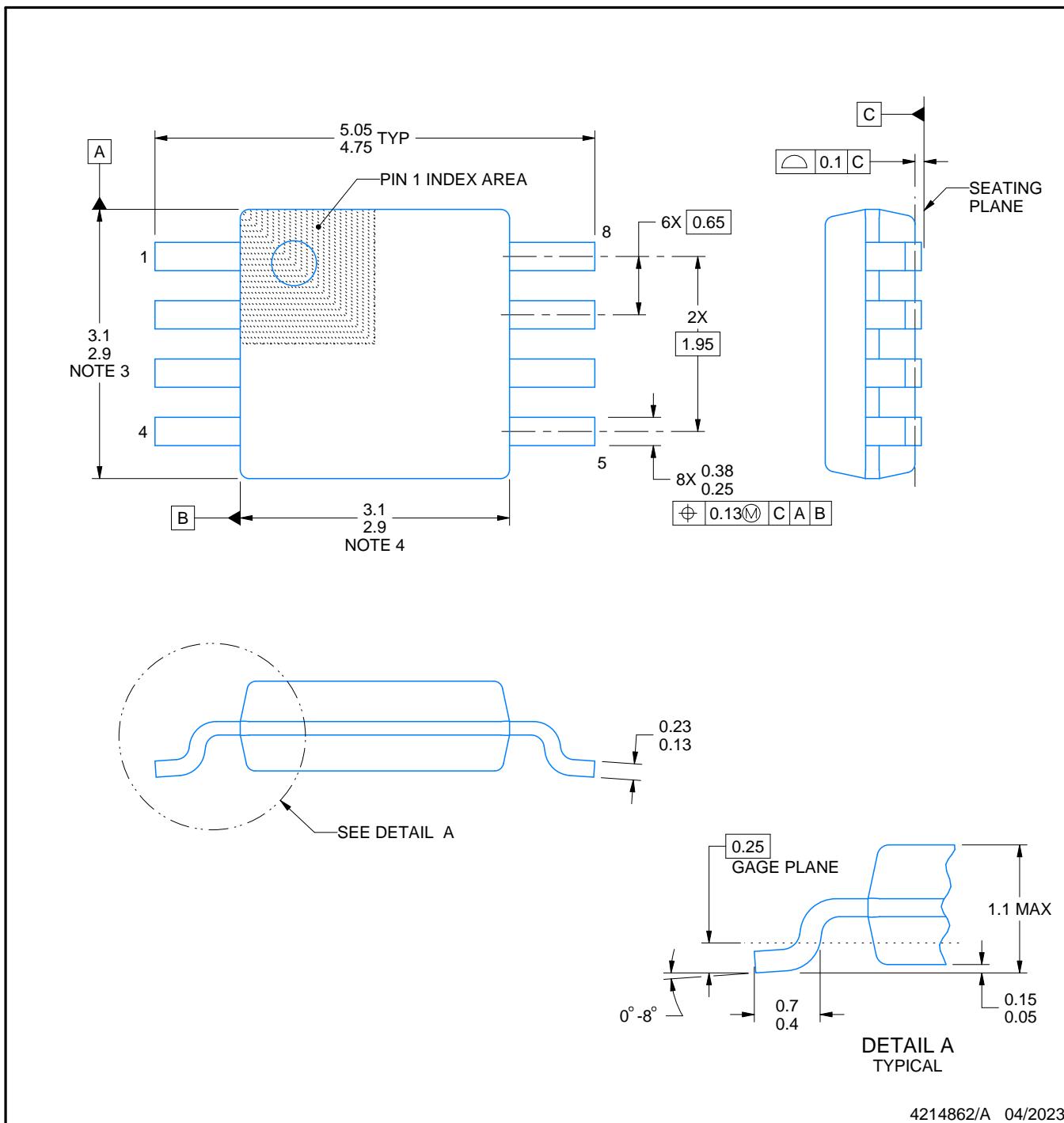
PACKAGE OUTLINE

DGK0008A



VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



NOTES:

PowerPAD is a trademark of Texas Instruments.

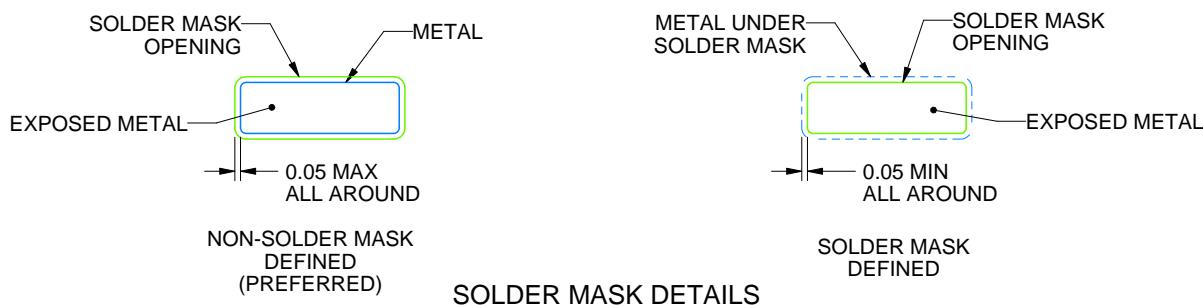
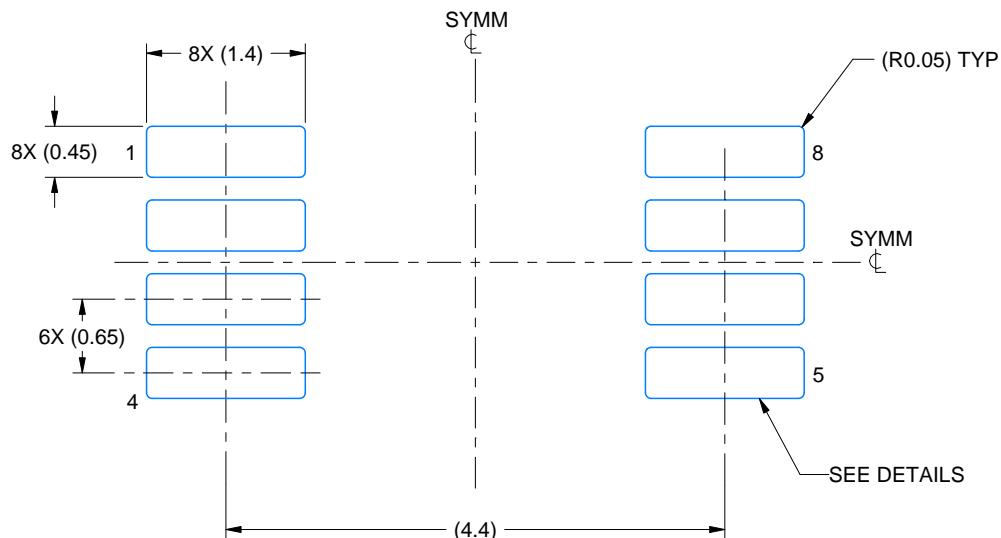
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-187.

EXAMPLE BOARD LAYOUT

DGK0008A

™ VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



4214862/A 04/2023

NOTES: (continued)

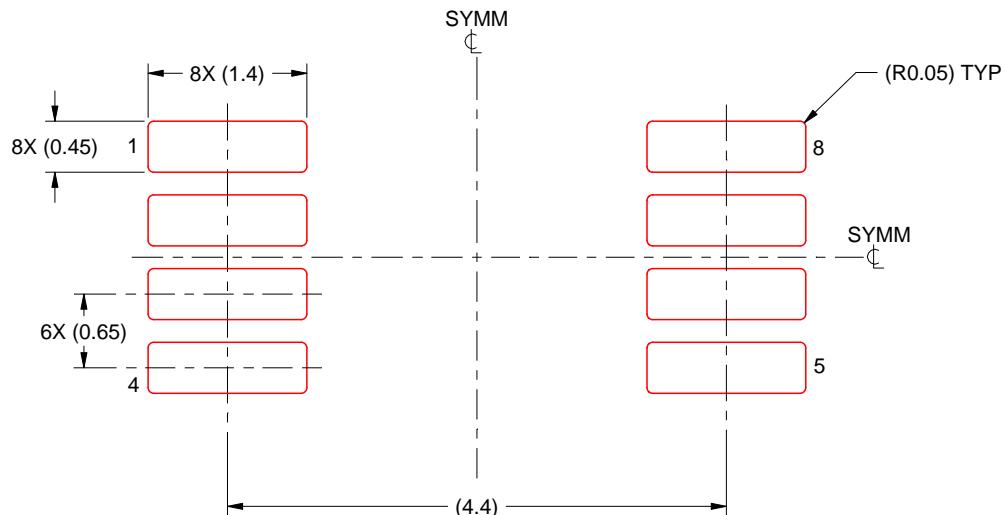
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.
9. Size of metal pad may vary due to creepage requirement.

EXAMPLE STENCIL DESIGN

DGK0008A

TM VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
SCALE: 15X

4214862/A 04/2023

NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

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